

8th/9th March // Ingolstadt

AGENDA

Reliability Testing and Protection

Day 1 // 8th March

Dr. Helmut Schweigart 13.30 // **Welcome**
ZESTRON Academy - Introduction of the agenda, ZESTRON and GfKORR
- Introduction of participants

Dr. Stefan Schoemaker 14.00 // **Reliability testing demands of LEDs for automotive and outdoor applications**
Quality Department Osram AG - Corrosive environments

Bálint Medgyes 14.45 // **Electrochemical migration (ECM) in the electronics**
Assistant Professor Electronics Technology
University of Technology and Economics (BME) - Types and sources of (ionic) contaminants
- ECM protection, test methods and models
- Scientific results and future works

15.30 // **Coffee Break**

Martin Wickham 16.00 // **Surface Insulation Resistance and Condensation Testing for Electronic Assemblies**
NPL National Physical Laboratory - Surface insulation resistance testing of printed circuit boards
- Conductive anodic filament testing of printed circuit boards
- Condensation testing to assess conformal coated assemblies

16.45 // **End of the first day**

Sightseeing & Dinner

18.30 // **City Tour**

Meeting point at Taschenturmtor in Ingolstadt (duration approx. 1 ¼ hours)

19.45 // **Dinner**

Exchange of experiences during a joint dinner in the restaurant "Schanzer Rutschn", Kanalstraße 1a

AGENDA

Reliability Testing and Protection

Day 2 // 9th March

Dr. Helmut Schweigart 09.00 // Summary of day 1
Head of Technology Department
ZESTRON Europe

Dr. Phil Kinner 09.15 // Selection of Conformal Coating
Technical Director – Coating
Devison
Electrolube

- Material selection based on end use considerations (with data)
- Potential failure mechanisms to be aware of
- Application methods with advantages and disadvantages

Rajan Ambat 10.00 // Hygroscopic residues on PCBA and humidity interaction
Department Mechanical
Engineering
Technical University of Denmark

- Hygroscopic potential from manufacturing process residues
- Electronic applications interact with humidity
- Water film formation depending from nature of (no clean) residues
- Influence on corrosion reliability of PCBA

10.45 // Coffee Break

Takahiro Horie 11.15 // Molding compound for power device
Staff Researcher
Encapsulation Department
Hitachi Chemical Co.,Ltd.
Japan

- Molding materials proposal for Requirement and Packaging type in Power Electronics
- Development Concepts of Molding Materials to meet Cu wire and High reliability of Power Electronics
- Hitachi Chemical Research and internal evaluation result

12.00 // Lunch

13.00 // End
